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Jang et al.

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(54) **ELECTRODE PLATE FOR SEMICONDUCTOR MANUFACTURING APPARATUS**

(71) Applicant: **ASM IP Holding B.V.**, Almere (NL)

(72) Inventors: **Hyun Soo Jang**, Daejeon (KR); **Jeong Ho Lee**, Seoul (KR); **Young Hoon Kim**, Cheonan-si (KR); **Jong Su Kim**, Cheonan-si (KR)

(73) Assignee: **ASM IP Holding B.V.**, Almere (NL)

(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-01**

(52) **U.S. Cl.**
USPC **D13/121**

(58) **Field of Classification Search**
USPC D23/259–265, 268–269, 233, 209, 235;
414/217, 935–941; D12/197; D13/182;
D15/144, 144.1; 118/715
CPC C23C 16/505; C23C 16/4407; C23C
16/4404; C23C 16/45565
See application file for complete search history.

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Primary Examiner — Eric Goodman

Assistant Examiner — Amy Wierenga

(74) *Attorney, Agent, or Firm* — Knobbe, Martens, Olson & Bear, LLP

(57) **CLAIM**

The ornamental design for an electrode plate for a semiconductor manufacturing apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of an electrode plate for a semiconductor manufacturing apparatus.
FIG. 2 is a front elevational view of the electrode plate.
FIG. 3 is a rear elevational view of the electrode plate.
FIG. 4 is a left side elevational view of the electrode plate.
FIG. 5 is a right side elevational view of the electrode plate.
FIG. 6 is a top plan view of the electrode plate.
FIG. 7 is a bottom plan view of the electrode plate; and,
FIG. 8 is a cross-sectional view taken along line 8-8 of FIG. 6.

1 Claim, 6 Drawing Sheets

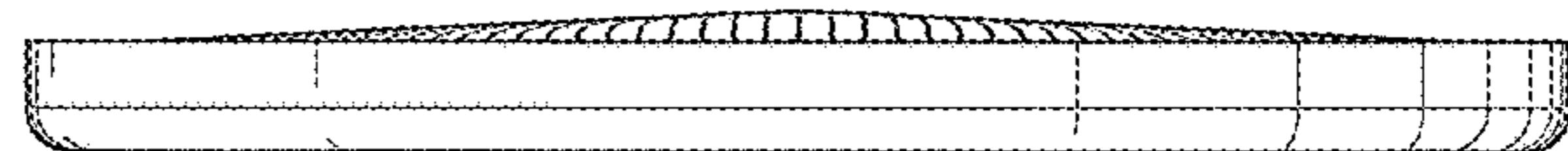
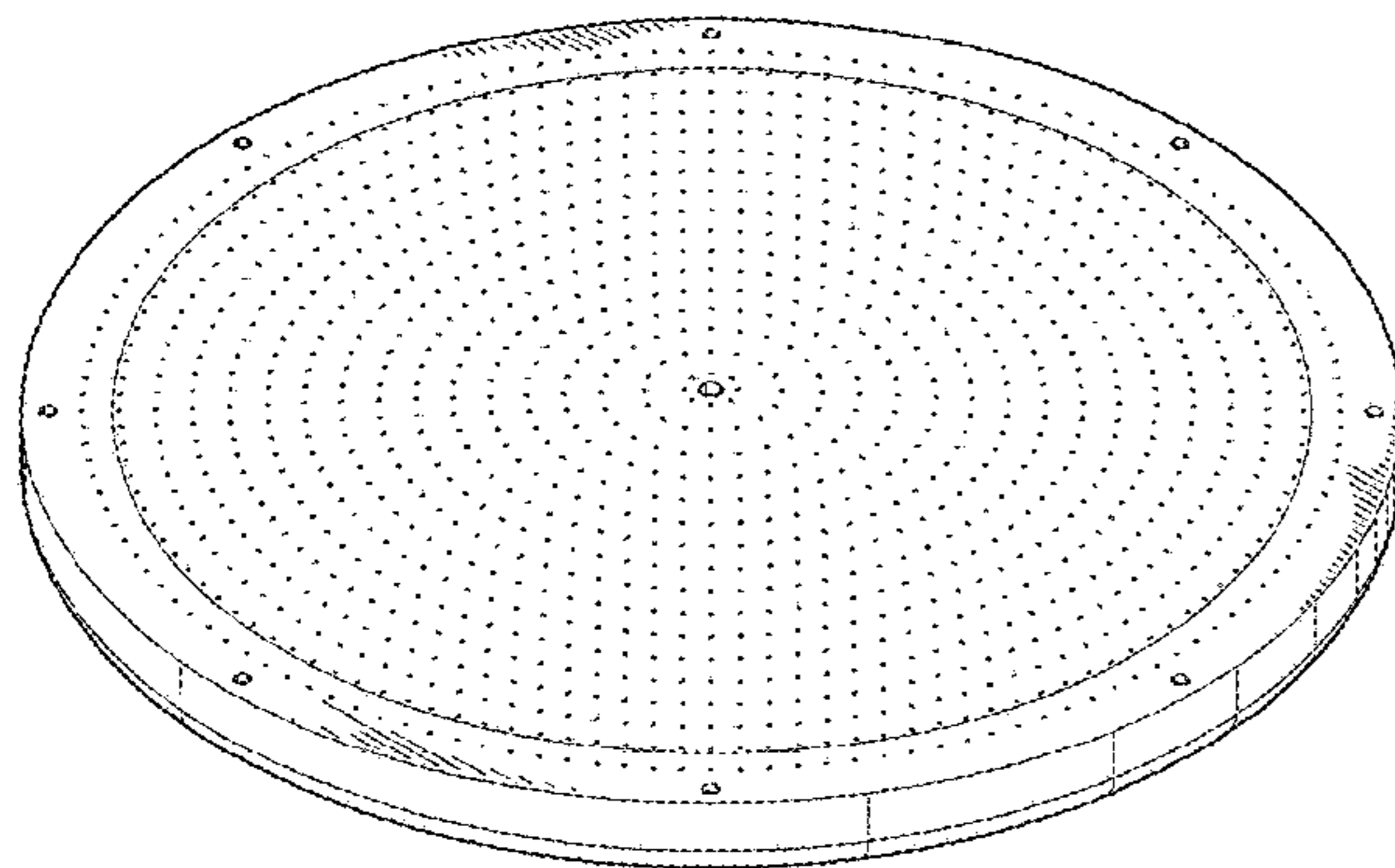


FIG. 1

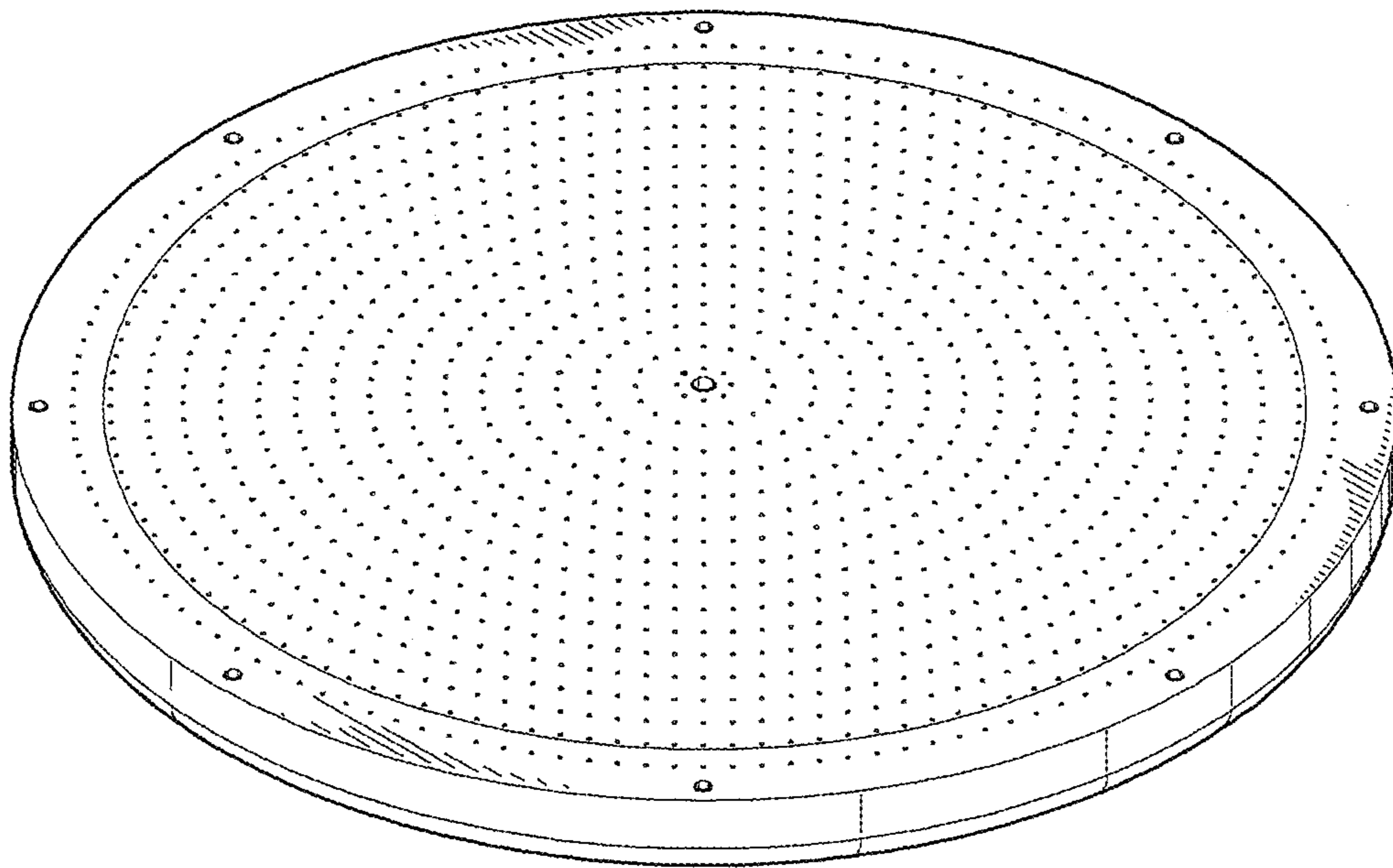


FIG. 2

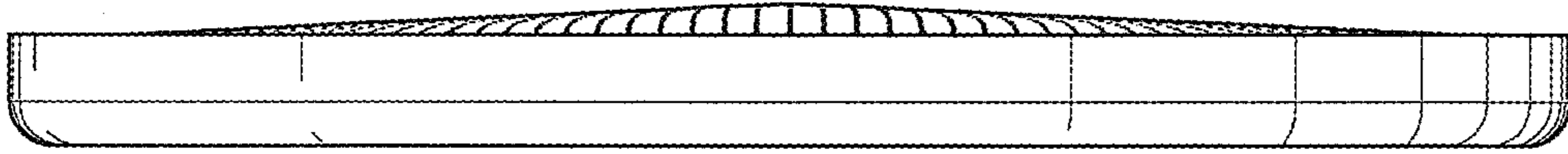


FIG. 3

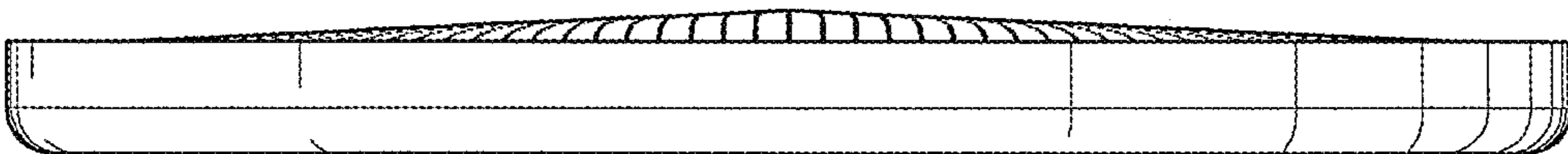


FIG. 4

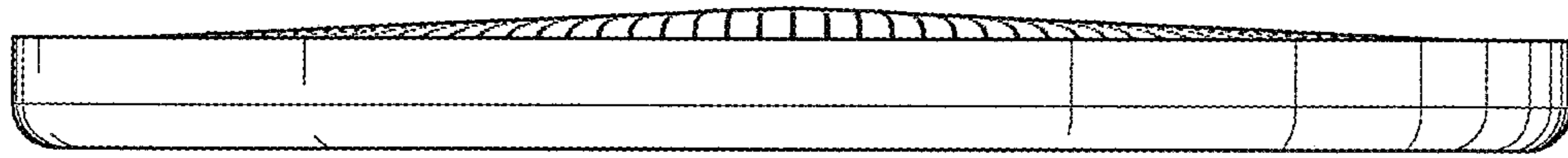


FIG. 5

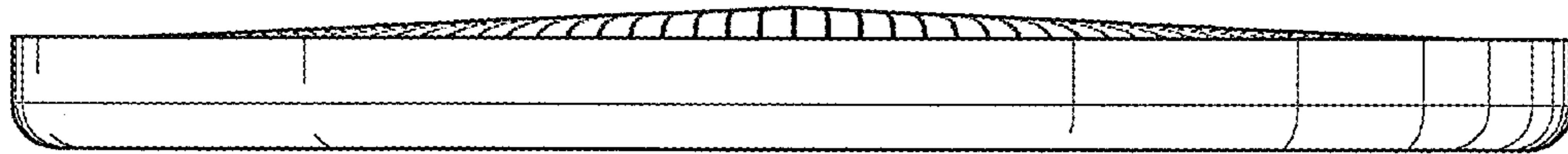


FIG. 6

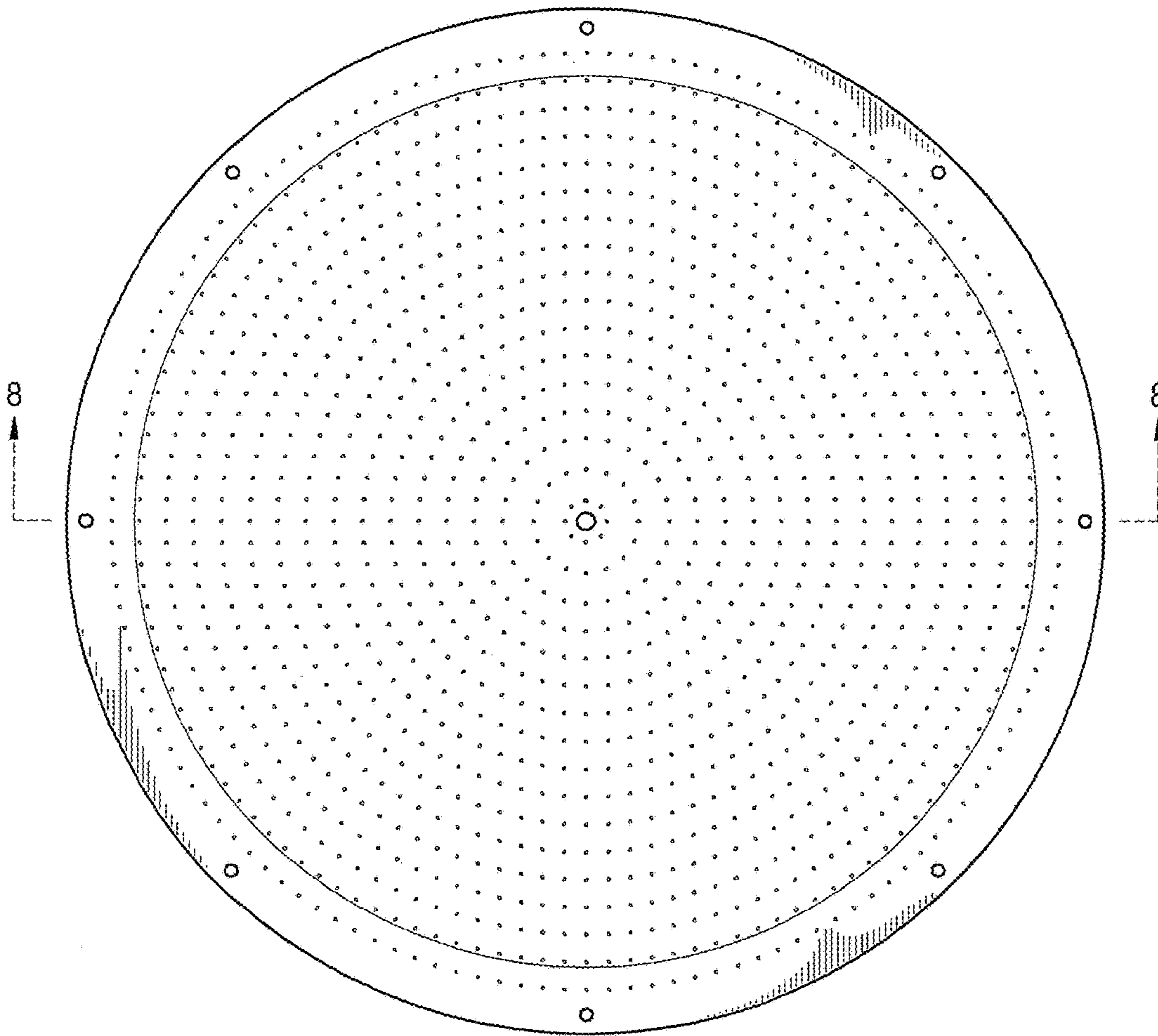


FIG. 7

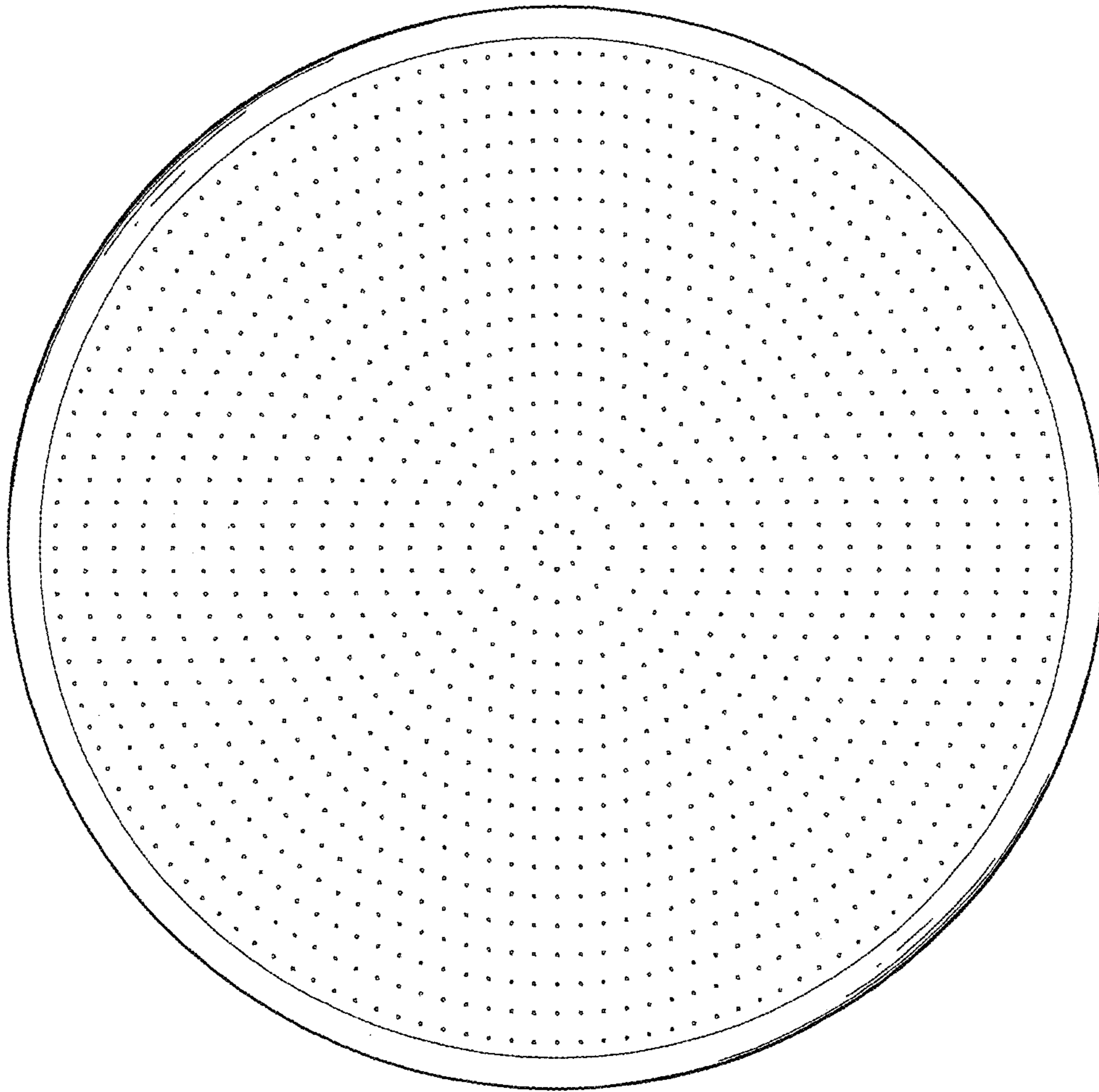


FIG. 8

